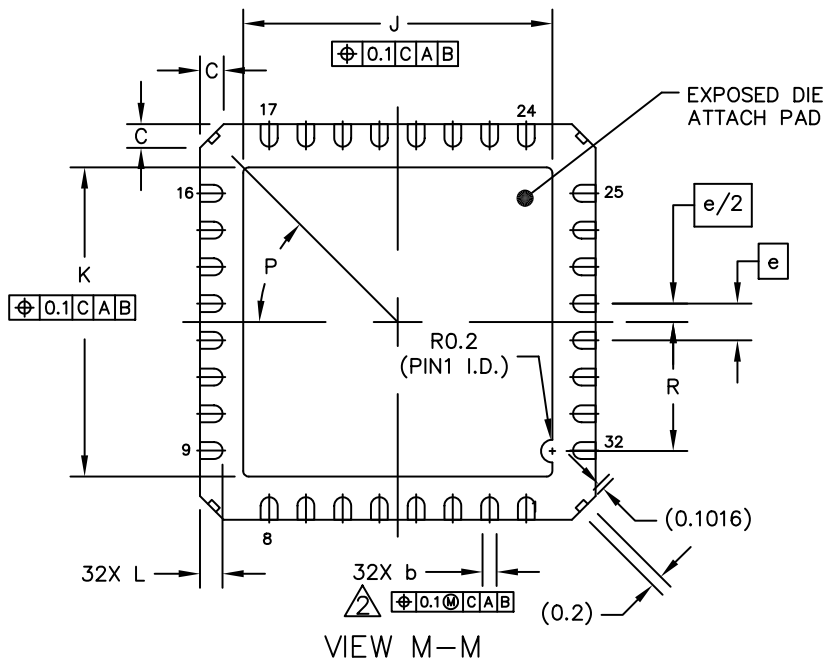
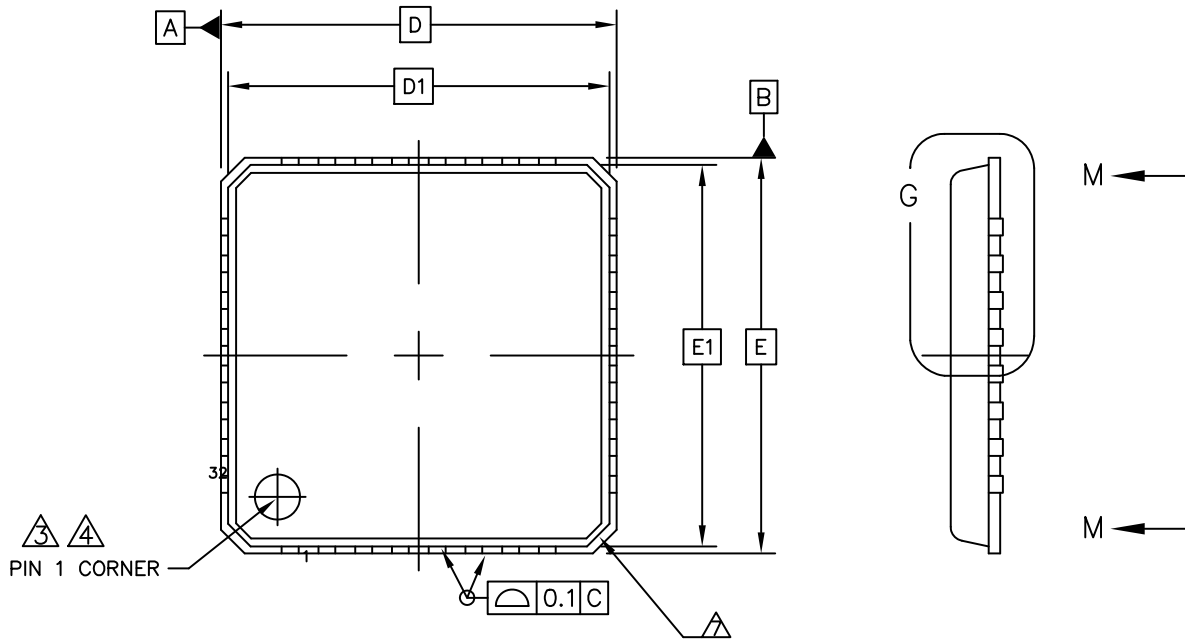


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

QFN32, 7x7
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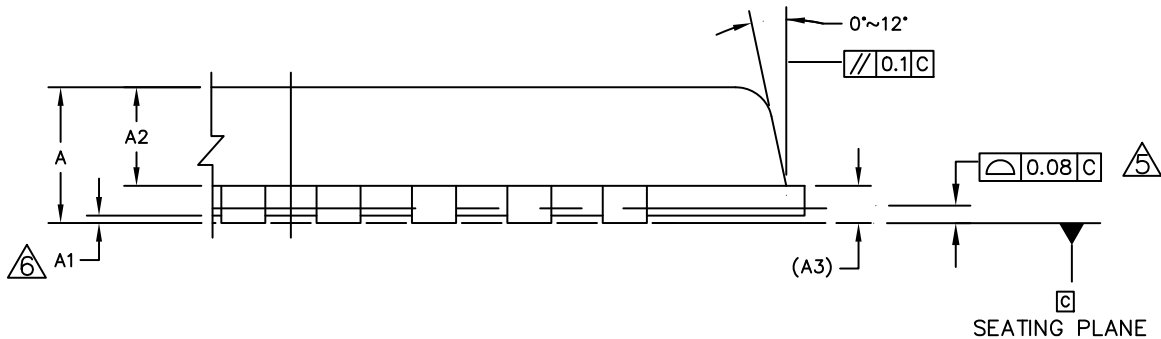
VIEW M-M

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DETAIL G
VIEW ROTATED 90° CLOCKWISE

DIM	MIN	NOM	MAX	NOTES
A	0.8		0.9	1. DIE THICKNESS ALLOWABLE IS 0.305mm MAXIMUM (.012 INCHES MAXIMUM) ⚠ DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.2 AND 0.25mm FROM TERMINAL TIP. ⚠ THE PIN #1 IDENTIFIER MUST BE PLACED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE OF PACKAGE BODY. ⚠ EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL. ⚠ APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING. ⚠ APPLIED ONLY TO TERMINALS. ⚠ EXACT SHAPE OF EACH CORNER IS OPTIONAL.
A1	0	0.02	0.05	
A2	0.576	0.615	0.654	
A3		0.203 REF.		
b	0.25	0.3	0.35	
C	0.24	0.42	0.6	
D		7 BSC		
D1		6.75 BSC		
E		7 BSC		
E1		6.75 BSC		
e		0.65 BSC		
J	5.37	5.47	5.57	
K	5.37	5.47	5.57	
L	0.35	0.4	0.45	
P		45° REF		
R	2.185		2.385	
		UNIT	DIMENSION AND TOLERANCES	
		MM	ASME_Y14.5M	JEDEC-MO-220-REV.F

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